

Abstract of the Disclosure

An interconnect includes a pad and at least two vias coupled to the pad. In one embodiment, the pad has five substantially straight edges, one via directly coupled to the pad by being formed substantially beneath the pad, and one via coupled to one of the five substantially straight edges by a tapered conductive segment. In another embodiment, the pad has three vias directly coupled to the pad and formed substantially beneath the pad. A method of forming an interconnect includes forming at least two vias in a substrate and coupling a pad to each of the at least two vias.

"Express Mail" mailing label number: EL600376447US

Date of Deposit: December 18, 2000

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.